



COMPANY INTRODUCTION

FORLINX - SETPEMBER, 2025



Forlinx Embedded

—
Trusted System on Module Partner



ABOUT FORLINX





19 yr
Founded on 2006



350+
Employees 150+ Developers



40k+
Enterprise clients



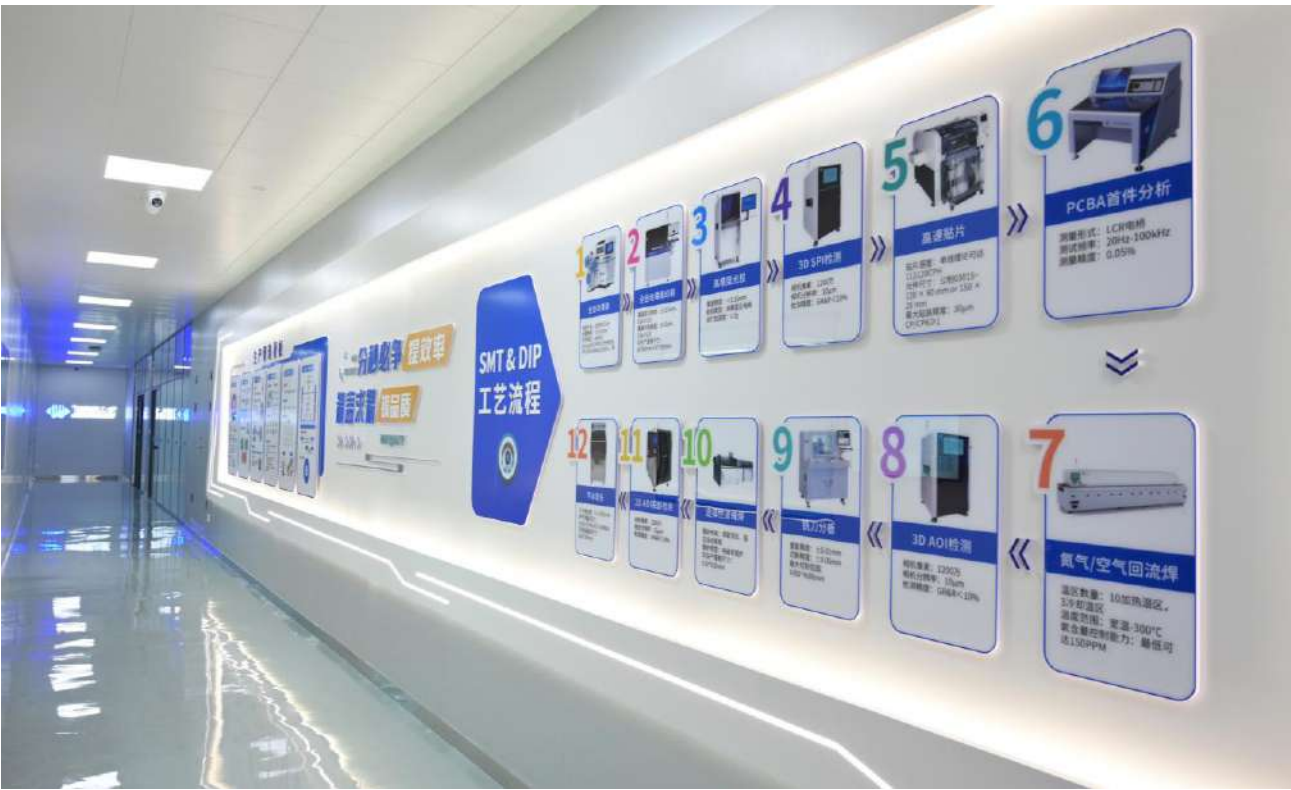
80k+
Supporting 80k+ developers



> 1M
Shipping Qty



31,000m²
R&D, Labs, and Factory



New SMT Lines

EMC Lab

We test all our products in the most extreme
electromagnetic conditions



10000 times
Cold start Assurance

Surge
Immunity

Electrostatic Discharge
Immunity

Interface
Conformance

Environmental Lab

We test all our products under the most extreme environmental conditions



▲
Low/High Temperature



▲
Salt Spray Testing



▲
Vibration



▲
Dropping

Quality Assurance System

The company adheres to ISO 9000 QMS and 6S standard managements, 100% aging and 100% full functional testing



Strict Supplier
Audit Mechanism



Manufacturing
Execution System(MES)



6S Management
system

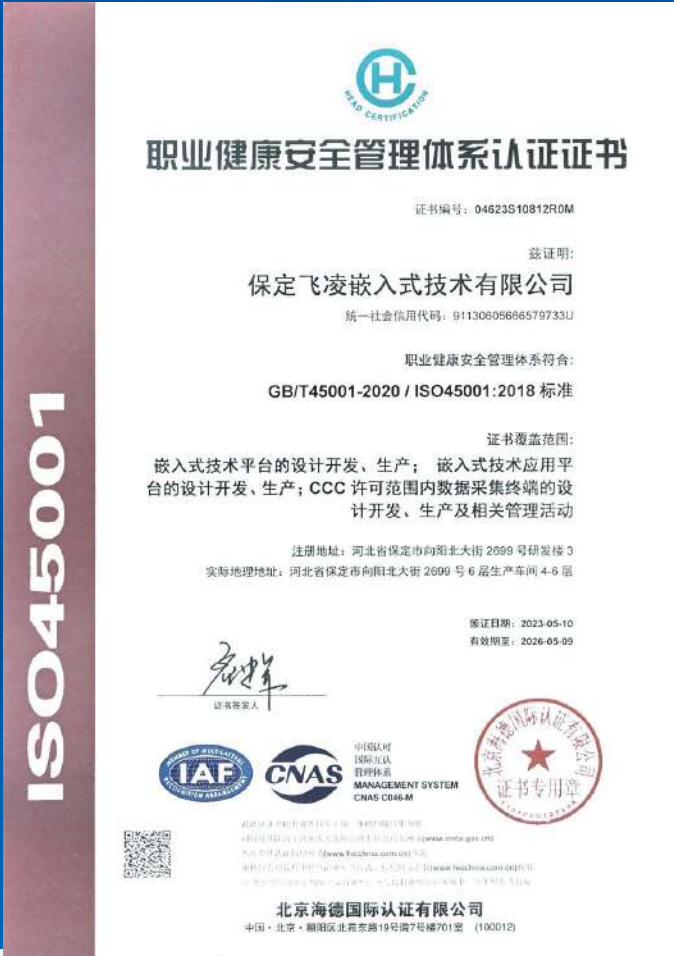


100% AOI
Inspection

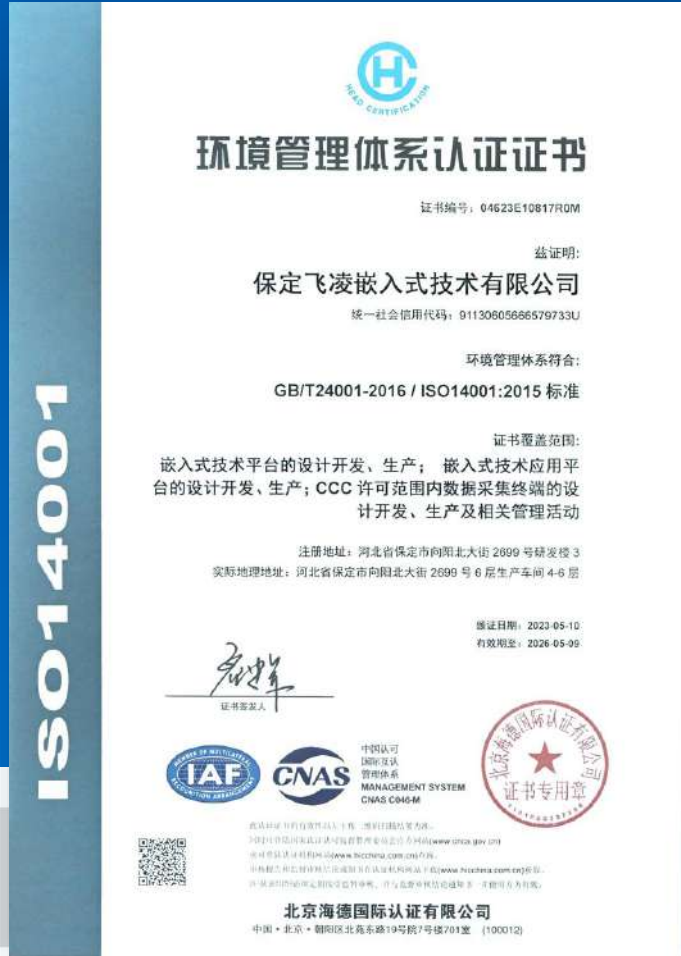
Quality Management System



ISO9001



ISO45001



ISO14001



ISO13485

Certification



CE/FCC/RoHS
Certified



Clients



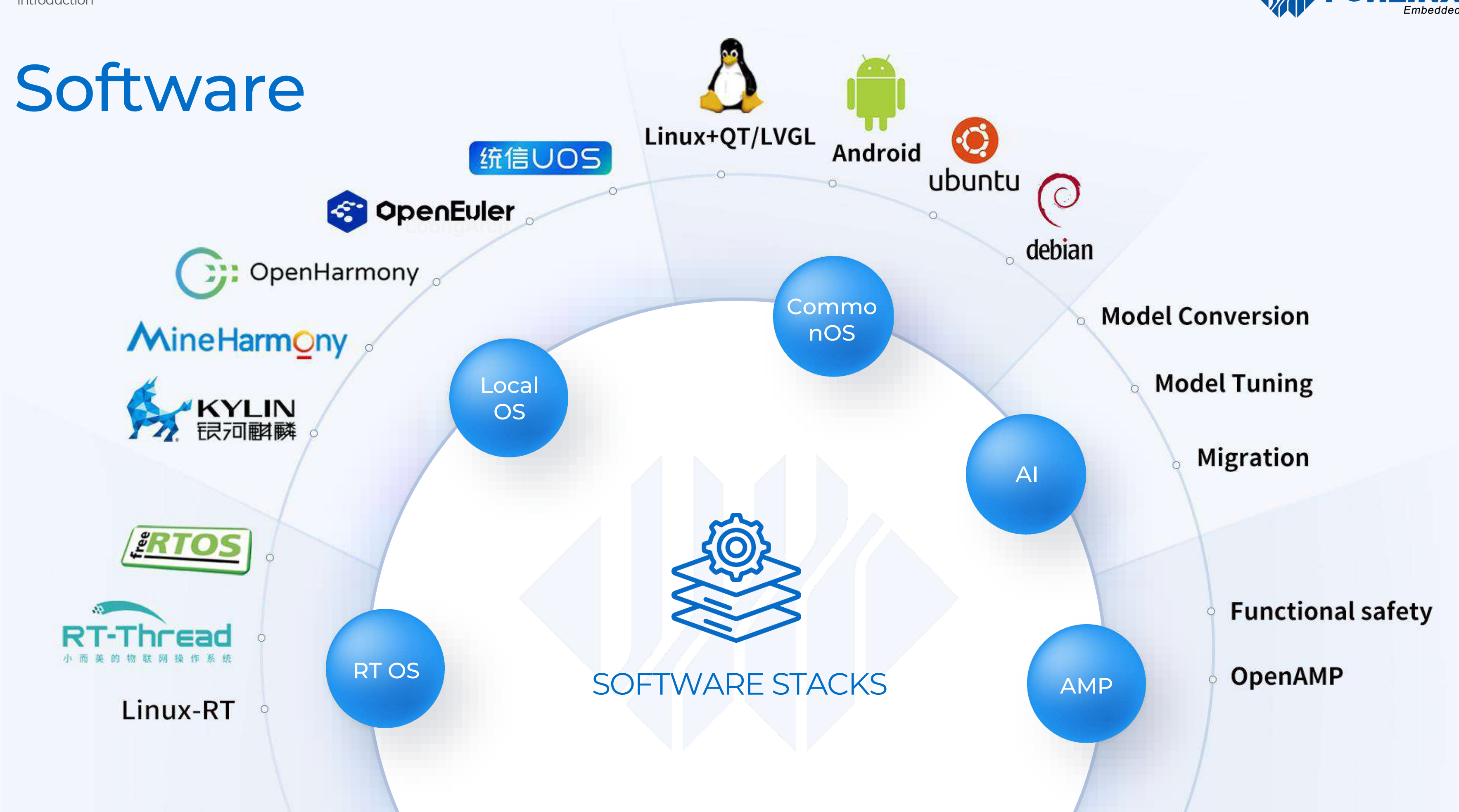
FORLINX HARDWARE PRODUCTS



Main Products



Software



System on Module Portfolios



i.MX 9 Series	FET-MX91xx-C / FET-MX9352-C / FET-MX95XX-C
i.MX 8 Series	FETMX8MPQ-C / FETMX8MPL-C / FETMX8MM-C
i.MX 6 Series	FETMX6UL-C / FETMX6ULL-C / FETMX6ULL-S / FETMX6DL-C / FETMX6Q-C
LS Series	FETI012A-C / FETI028A-C / FETI043A-C / FETI046A-C
i.MX RT Series	FETI052-C / FETI061-S



AM62 Series	FET6254-C / FET6232-C / FET6231-C
AM3354 Series	FET335xS-II / FET-335xS / FET-335xD



RK3588 Series	FET3588-C / FET3588J-C
RK3576 Series	FET3576-C / FET3576J-C
RK3399 Series	FET3399-C / FET3399K-C
RK3568 Series	FET3568-C / FET3568J-C
RK3562 Series	FET3562-C / FET3562J-C
RK3506 Series	FET3506J-C / FET3506-S



T527	FET527N-C / FET527-C
T507	FETT507-C / FET507-S
T3	FETT3-C-C / FET-T3-S
A40i	FETA40i-C
T536	FET536-C / FET536-S
T113-i	FET113i-S



JH7110	FET7110-C
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D9360	FET-D9360-C
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G2L Series	FET-G2LD-C
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MA35	FET-MA35-S2
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SOC Partners

I ARM



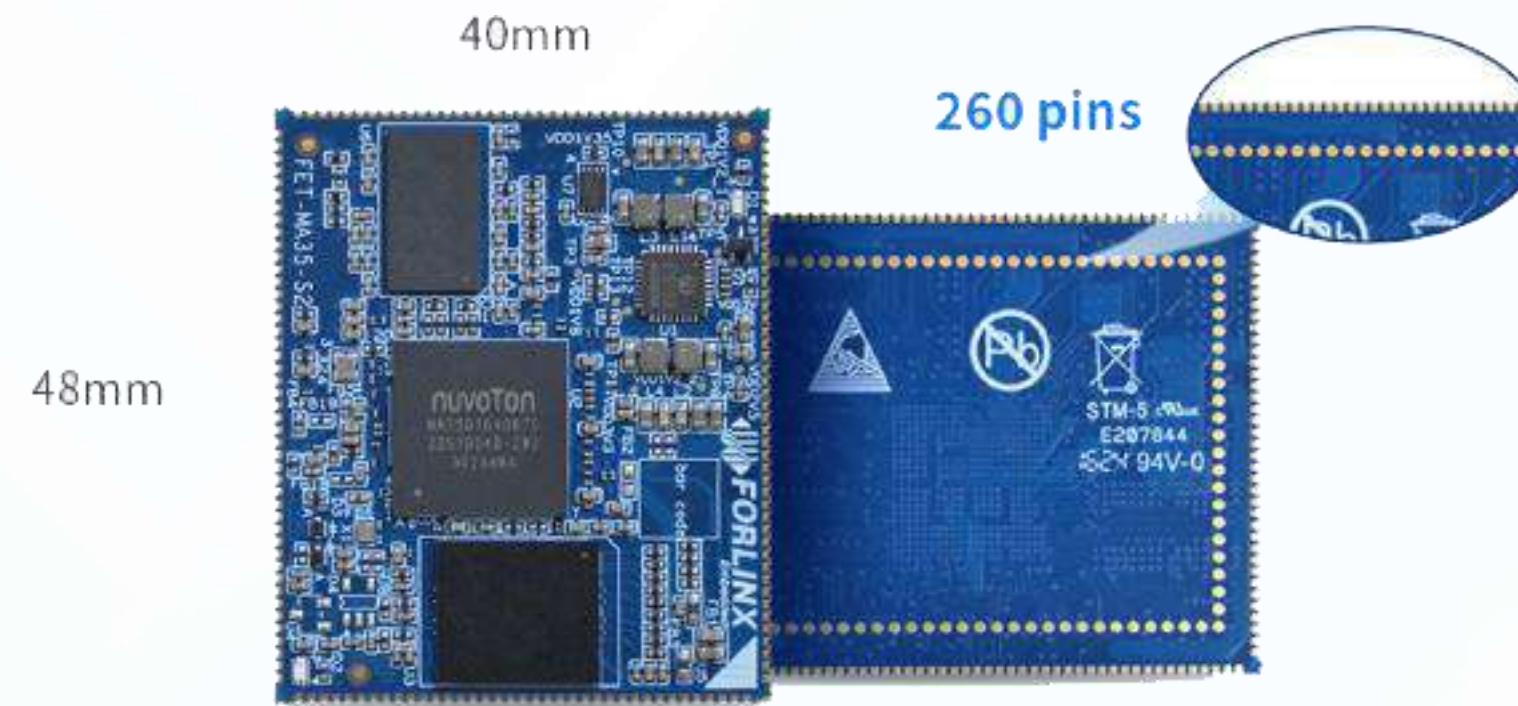
I RISC-V



I LoongArch



Nuvoton



FET-MA35-S2 SoM

CPU: Nuvoton MA35D1

Architecture: 2xCortex-A35@800MHz + Cortex-M4@180Mhz

RAM: 512MB/1GB DDR3L

ROM: 8GB eMMC

UART: up to 17x

Ethernet: 2 x 1000M

System: Linux 5.10.140

RGB: 1920x1080

MIPI CSI: 2 x 4 lane, 3M Pixels

PWM: up to 18x

ADC: up to 8 channels, 10 bit, 500k SPS

EADC: up to 8 channels, 10 bit, 4.7M SPS

GPIO: up to 208

AI SOC Partners



Forlinx

Data Acquisition

Model Training

Model Conversion

AI SDK

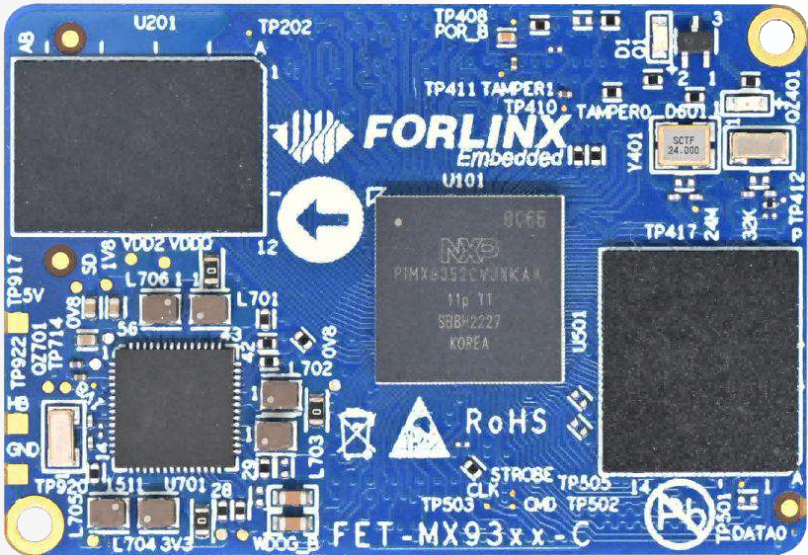
AI Frameworks



RKNN



NXP - i.MX 9 Series



FET-MX9352-C SoM

CPU: NXP i.MX9352

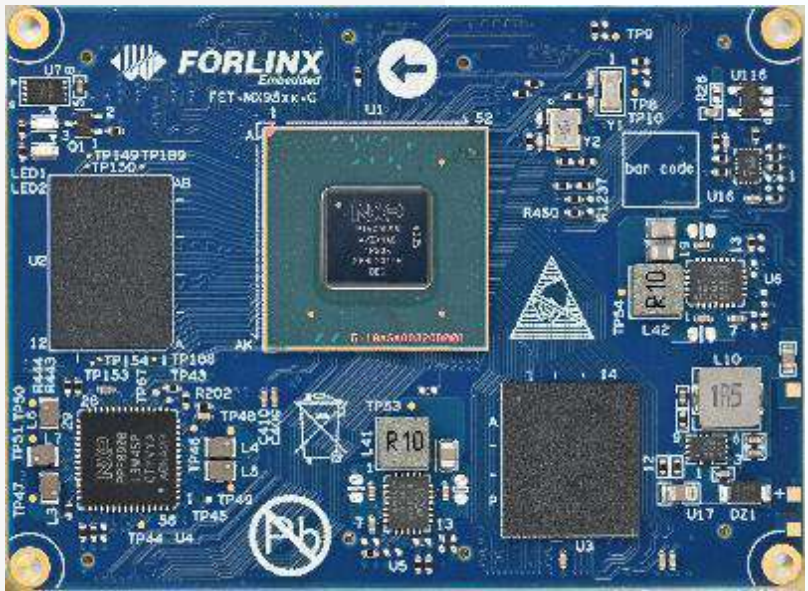
Architecture: 4 x A55 + M33

NPU: 0.5 TOPS

RAM: 1GB LPDDR4

ROM: 8GB eMMC

System: Linux 5.15.52+Qt 6.3.2



FET-MX95XX SoM

CPU: NXP i.MX9596

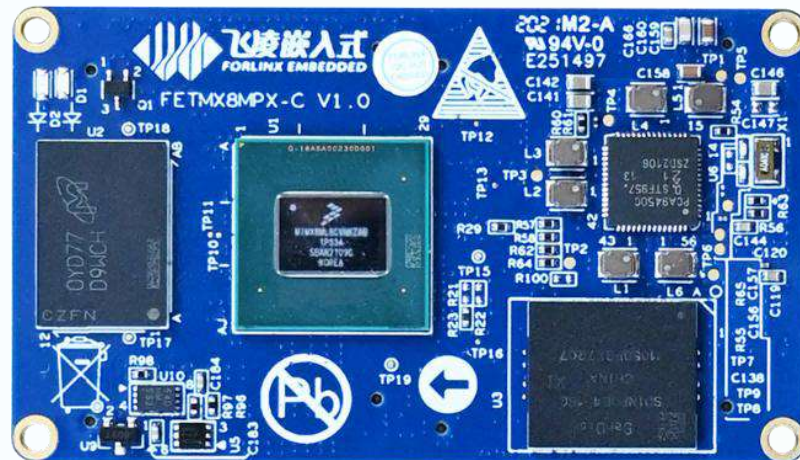
Architecture: 6 x A55 + M7 + M33

NPU: 2 TOPS

RAM: 8GB LPDDR4

ROM: 64GB eMMC

NXP - i.MX 8 Series



FETMX8MP-C SoM



FETMX8MP-Smarc SoM



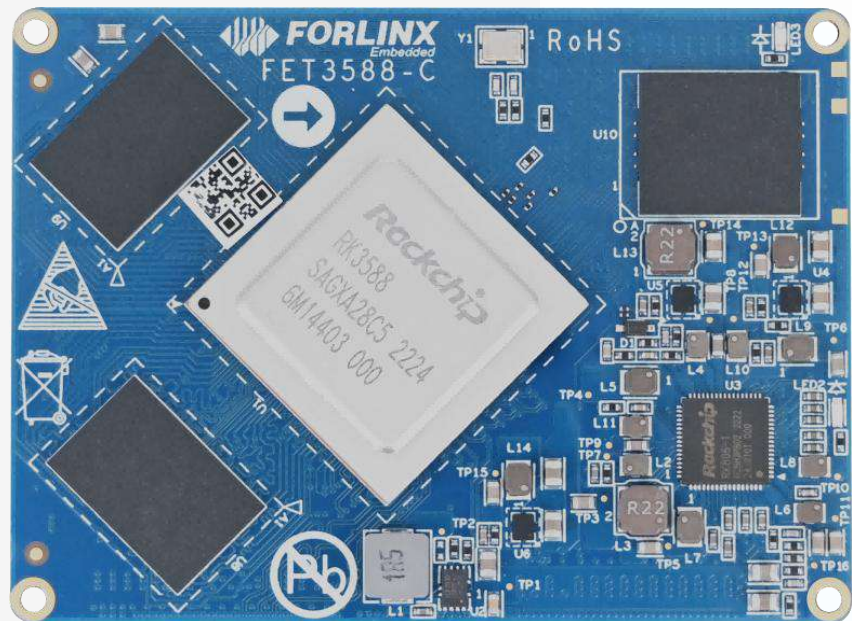
FETMX8MM-CSoM

CPU: i.MX8M Plus
Architecture: 4xCortex-A53+Cortex-M7
Frequency: 1.6GHz
RAM: 1/2/4GB LPDDR4
ROM: 8/16GB eMMC
System: Linux5.4.70+Qt5.15, Android11.0

CPU: i.MX8M Plus
Architecture: 4xCortex-A53+Cortex-M7
Frequency: 1.6GHz
RAM: 2/4GB
ROM: 16GB eMMC
System: Linux6.1.36

CPU: i.MX8M Mini
Architecture: 4xCortex-A53+Cortex-M7
Frequency: 1.8GHz
RAM: 2GB DDR3
ROM: 8GB eMMC
System: Linux4.14.78+Qt5.10.1, Android9.0

Rockchip



FET3588-C SoM

CPU: RK3588/RK3588J

Architecture: 4xCortex-A76 + 4xCortex-A55

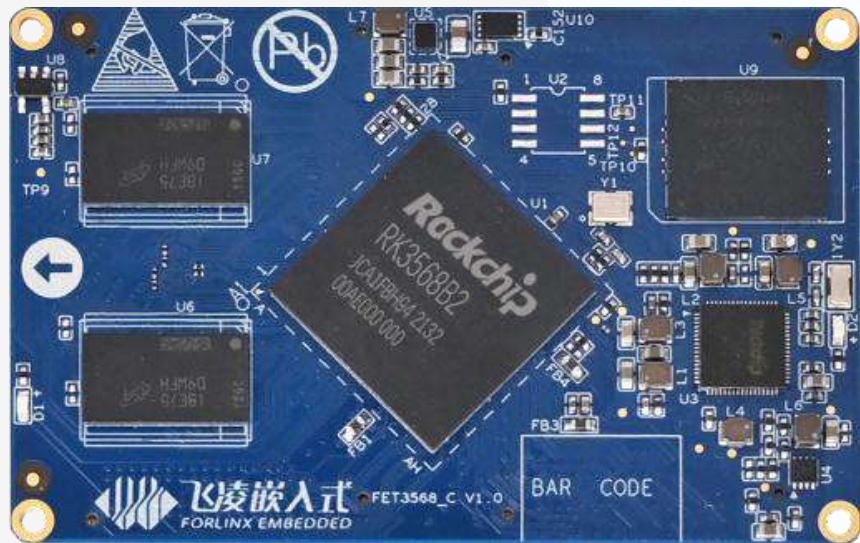
Frequency: 2.4GHz

NPU: 6 TOPS

RAM: 4GB/8GB DDR4x

ROM: 32GB/64GB eMMC

System: Linux5.10/Android12.0/Forlinx
Desktop 20.04



FET3568-C SoM

CPU: RK3568/3568J

Architecture: 4x Cortex-A55

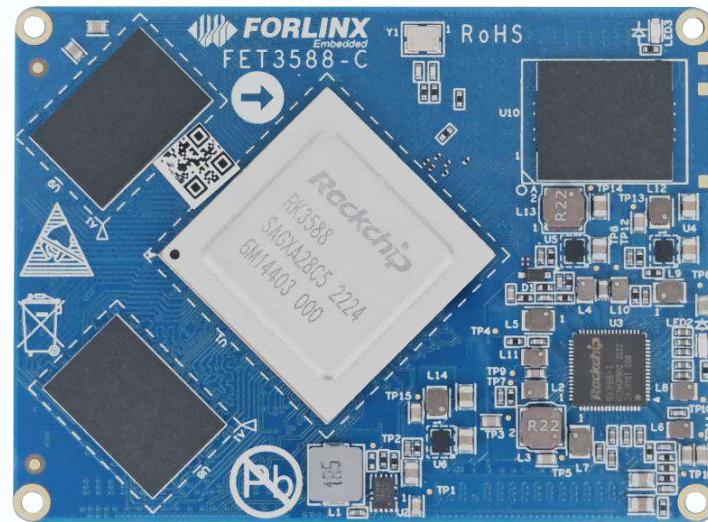
Frequency: 2.0GHz

RAM: 2GB/4GB DDR4

ROM: 16GB eMMC/32GB eMMC

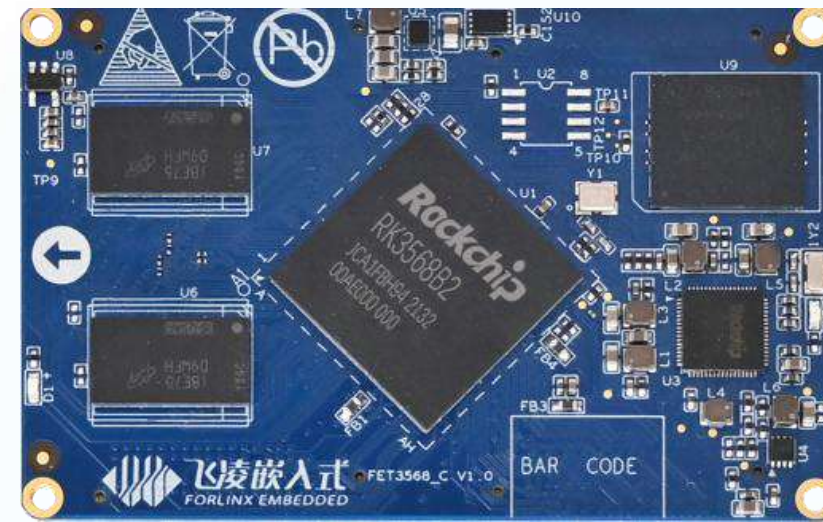
System:
Linux4.19,Android11.0,ForlinxDesktop
20.04, Debian

Rockchip



FET3562-C SoM

CPU: RK3562/RK3562J
Architecture: 4xCortex-A53
Frequency: 2.0GHz, 1.8GHz
NPU: only available for commercial grade one
RAM: 1GB/2GB DDR4x
ROM: 8GB/16GB eMMC
System: Linux5.10.198+QT5.15/AndroidTBD/AMPTBD



FET3576-C SoM

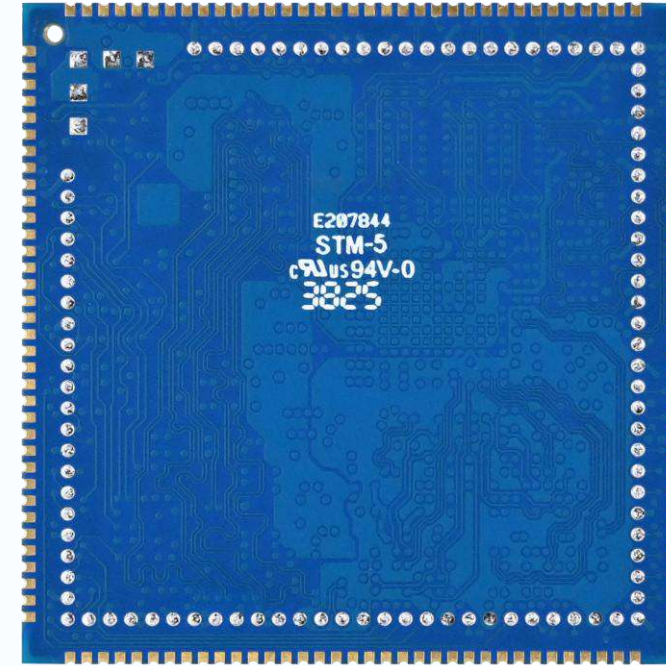
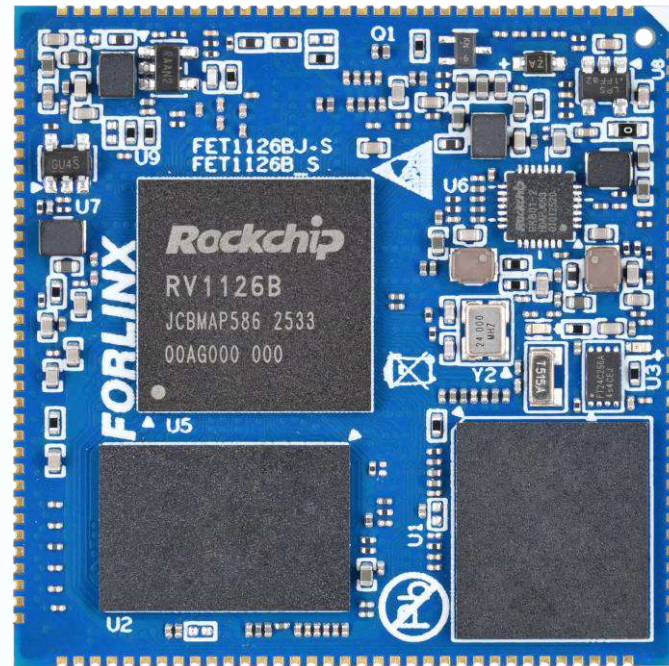
CPU: RK3576
Architecture: 4xCortex-A72+4xCortex-A53
Frequency: 2.3GHz+2.2GHz
NPU: 6 TOPS
RAM: 2GB/4GB LPDDR4
ROM: 32GB eMMC
System: Linux6.1.57, AndroidTBD



FET3399-C SoM

CPU: RK3399/RK3399K
Architecture: 2xCortex-A72+4xCortex-A53
Frequency: 1.8GHz, 1.4GHz
RAM: 2GB/4GB LPDDR3
ROM: 16/32GB eMMC
System: Linux 4.4.189+Qt5.12, Android7.1,
ForlinxDesktop 18.04

Rockchip



FET1126B-S SoM

CPU: RK1126B

Architecture: 4xCortex-A53

Frequency: 1.5GHz

NPU: 3 TOPS

RAM: 4GB DDR4x

ROM: 64eMMC

System: Linux 6.1.118

UART: up to 8x

Ethernet: 100M

RGB: 1920x1080@60fps

MIPI DSI: 4 lane, 1.5Gbps/lane

MIPI CSI: 2 x 4 lane, 2.5Gbps/lane

PWM: up to 27x

ADC: up to 24 channels, 13 bit, 2MSPS

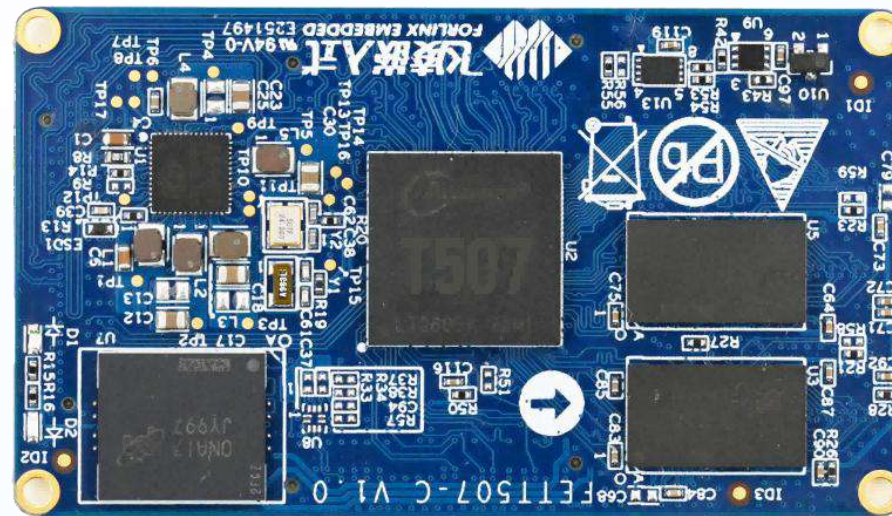
GPIO: up to 118

Allwinner



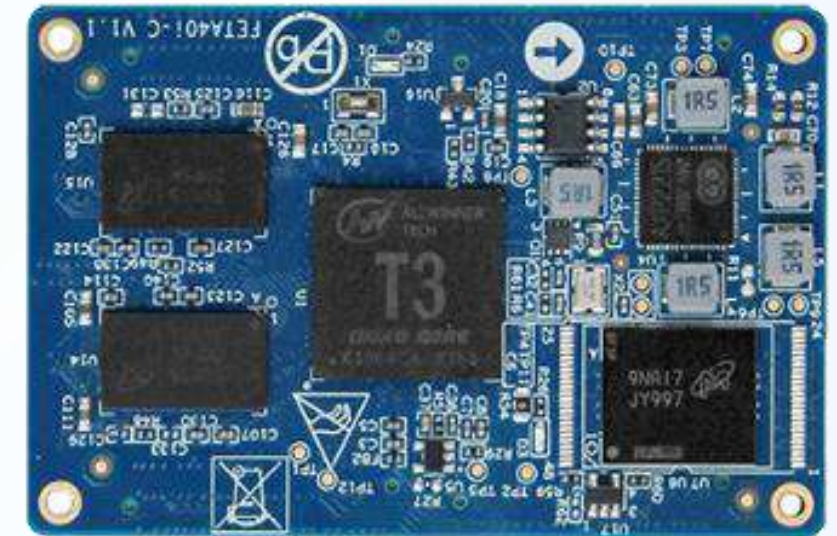
FETA40i-C SoM

CPU: A40i-H
Architecture: 4x Cortex-A7
Frequency: 1.2GHz
RAM: 1GB/2GB DDR3
ROM: 8GB eMMC
System: Linux3.10, Linux5.10, Android7.1



FETT507-C SoM

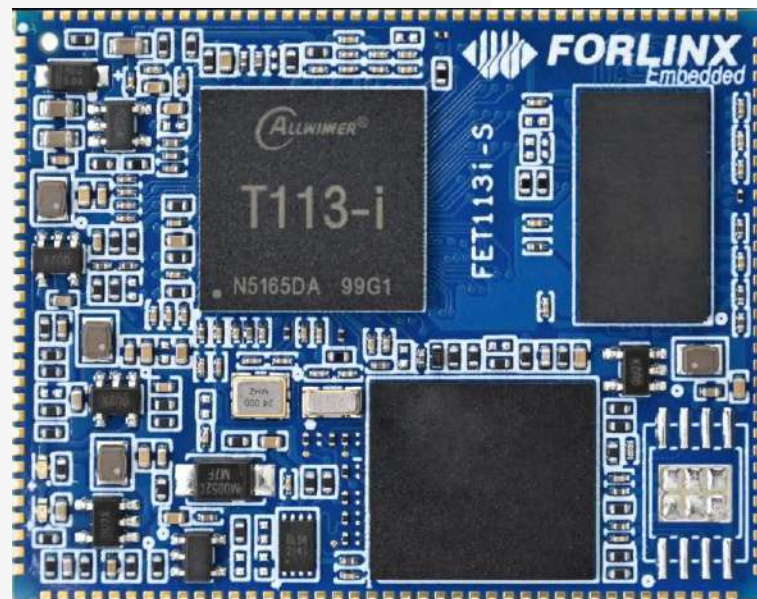
CPU: T507-H
Architecture: 4x Cortex-A53
Frequency: 1.5GHz
RAM: 1GB/2GB DDR3
ROM: 8GB eMMC
System: Linux4.9+Qt5.12, Android10.0,
Ubuntu18.04



FETT3-C SoM

CPU: T3
Architecture: 4x Cortex-A7
Frequency: 1.2GHz
RAM: 1GB DDR3
ROM: 8GB eMMC
System: Linux3.10+Qt5.9

Allwinner



FET113i-C SoM

CPU: T113i

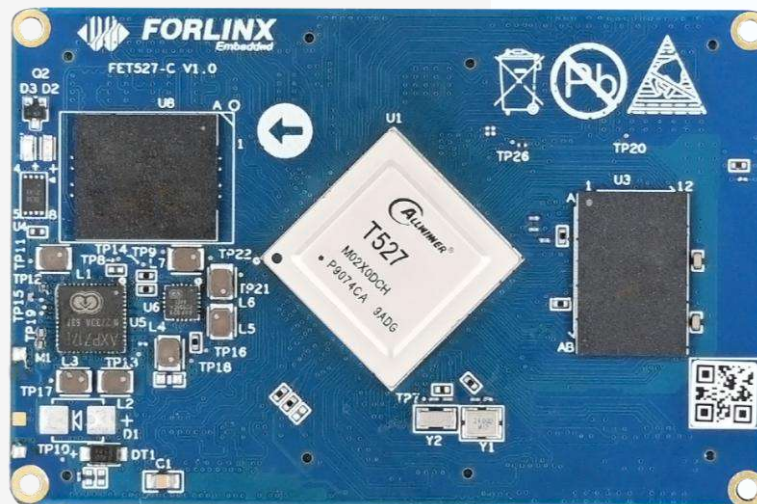
Architecture: 2xCortex-A7+RISC-V+DSP

Frequency: 1.2GHz

RAM: 512/256MB DDR3L

ROM: 8GB eMMC/256MB SPI Nand Flash

System: Linux5.4.61



FET527N-C SoM

CPU: Allwinner T527 (T527M02X0DCH)

Architecture: 4xCortex-A55@1.8GHz +

4xCortex-A55@1.4GHz

RAM: 2GB/4GB LPDDR4

ROM: 16GB/32GB eMMC

System: Linux 5.15.104, Android

Embedded Computer

FCU2601 Energy Management System

Architecture: 4xCortex-A55@1.8GHz

RAM: 2GB/4GB DDR4

ROM: 16GB/32GB eMMC

Support: Docker, MySQL, FTP Server, ModBus-TCP, ModBus-RTU, OpenVPN, MQTT



Embedded Computer



FCU2401 Economical ARM
Embedded Computer

CPU: A40i
Architecture: Cortex-A7
Frequency: 1.2GHz
RAM: 1GB DDR3L
ROM: 8GB eMMC
System: Linux3.10+QT5.9



FCU1101 Economical
4G Gateway

CPU: i.MX6UltraLite
Architecture: Cortex-A7
Frequency: 528MHz
RAM: 256MB DDR3, 512MB DDR3L
ROM: 256MB/1GB NandFlash
System: Linux3.14



High Performance 4G
Gateway/Controller

CPU: i.MX6DL
Architecture: Cortex-A9
Frequency: 1GHz
RAM: 1GB DDR3
ROM: 8GB eMMC
System: Linux3.0.35+Qt4.8.5, Android6.0

Embedded Computer

FDU Embedded Computer

Model: FDU070K02 & FDU101K02

Architecture: 4xCortex-A53

Frequency: 1.5GHz

RAM: 2GB DDR3

ROM: 8GB eMMC

System: Linux4.9.170, Android10

Screen: Adapted to 10.1-inch screen (1280*800 resolution) and 7.0-inch screen (1024*600 resolution)



Embedded Computer



FCU1103 All-in-one 4G
Gateway/Controller

CPU: i.MX6UltraLite
Architecture: Cortex-A7
Frequency: 528MHz
RAM: 256MB DDR3, 512MB DDR3L
ROM: 256MB NandFlash, 8GB eMMC
System: Linux4.1.15+Qt5.6



FCU1104 Extended
4G Gateway

CPU: i.MX6ULL
Architecture: Cortex-A7
Frequency: 800MHz
RAM: 256MB DDR3, 512MB DDR3L
ROM: 256MB NandFlash, 8GB eMMC
System: Linux4.1.15



FCU3001 AI Edge
Computing Terminal

Main Control: NVIDIA® Jetson NX
RAM: 16GB LPDDR4x
ROM: 16GB eMMC+MicroSD card expansion
System: Ubuntu 18.04

Display Modules



7.0" MIPI Display

Resolution: 1024*768
Interface: FPC connector
Type: capacitive touching
Range: -20°C ~ +70°C



7.0" Capacitive Display

Resolution: 1024*768, 800*480
Interface: FPC connector
Type: capacitive touching
Range: -20°C ~ +70°C



10" LVDS Display

Resolution: 1280*800
Interface: LVDS
Type: capacitive touching
Range: -20°C ~ +70°C



4.3" Resistive Display

Resolution: 480*272
Interface: FPC connector
Type: capacitive touching
Range: -20°C ~ +70°C

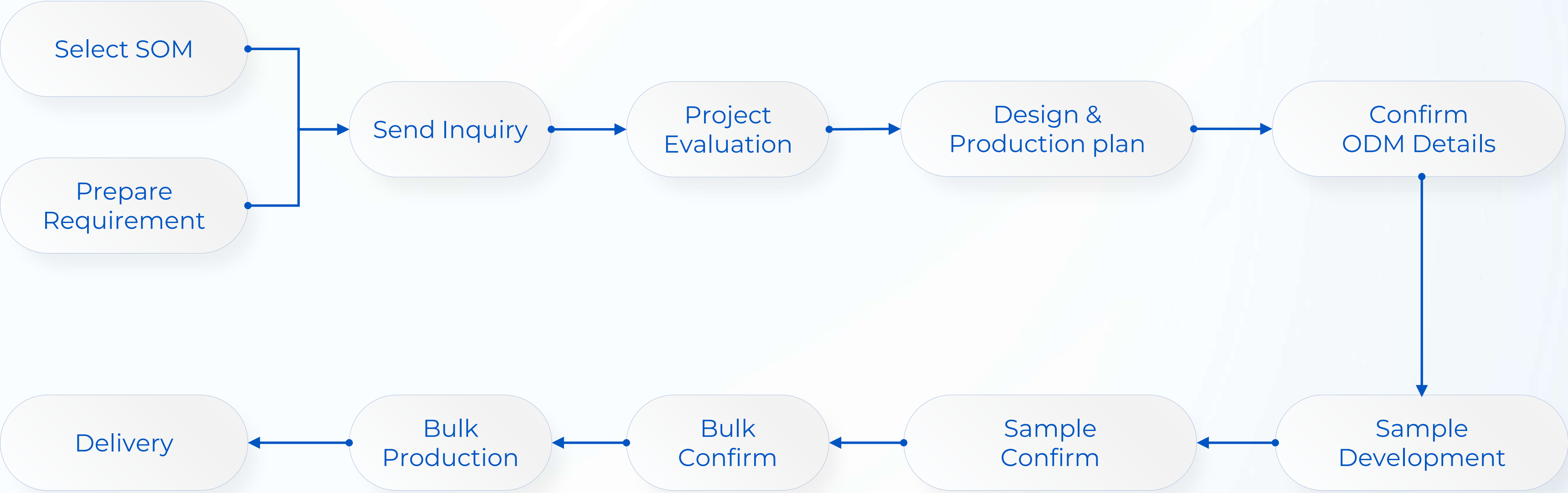
TECHNICAL SUPPORT



Technical Support



ODM Service



FORLINX SOLUTIONS



Major Industries



Smart Electric Power



▲ Charge Pile



▲ Battery Detection

- Intelligent Distribution Terminal
- Electricity Information Collection
- Power Communication Equipment
- Electricity Instrumentation
- Electricity Fire Alarm System
- Substation Inspection Equipment



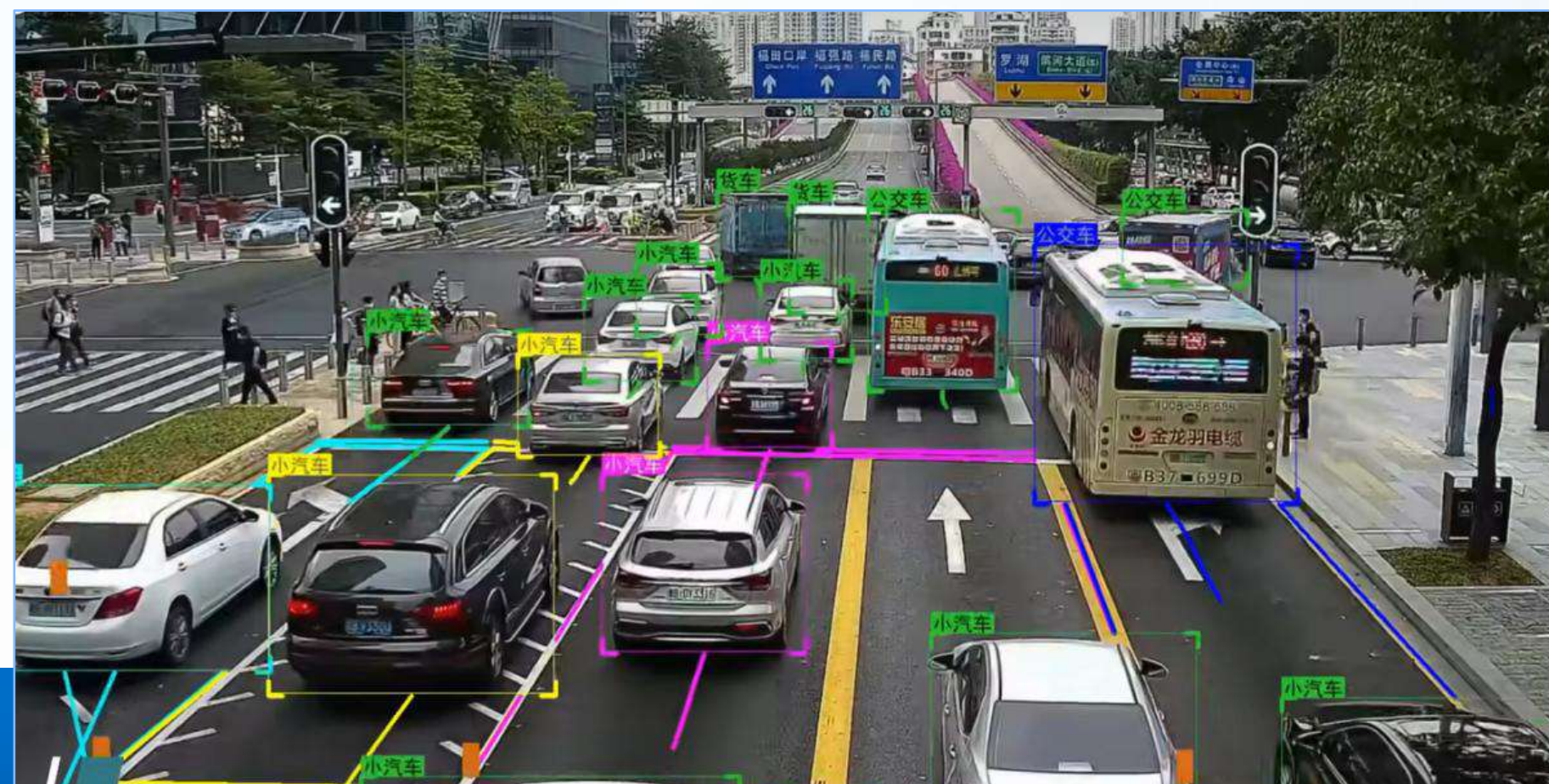
▲ Protocol Converter



▲ EMS for Energy Storage

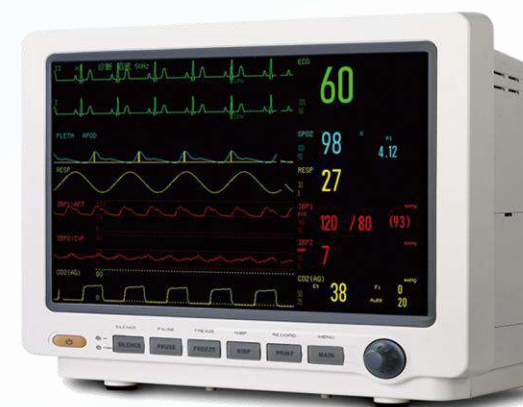
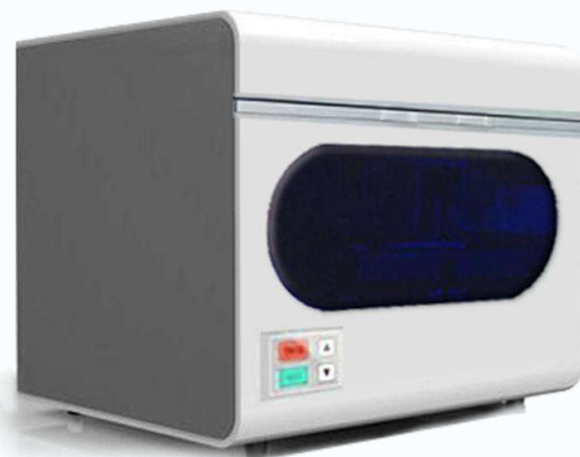
Intelligent Transportation

- Electronic Bus Stop Board
- High-speed ETC RSU
- Subway Gate
- Intelligent Public Transportation All-in-One
- Intelligent Driving Exam Car End
- V2X
- Traffic Light



Intelligent Medical

- Nucleic Acid Extractor
- Monitor (device)
- Luminescent Immunoassay Analyzer
- Blood Analyzer
- Ventilator
- Myopia Treatment Equipment
- Ultrasound Scalpel



Smart Industry



▲ Robot Arm



▲ Inkjet Printer



▲ Industrial Gateway



▲ CNC Machine Tools



▲ AGV Trolley



▲ Industrial Camera



▲ 3D Printer

Smart City



01

DIDI
Charge
Pile



02

Lenovo
Edge
Computing
Gateway



03

Smart
Parking



04

Unmanned
Supermarket
Project

Smart Agriculture

▼ Agricultural Greenhouse Gateway



Smart Navigation for
Agricultural Machines ▼



Straw Baling Machine ▲

▼ Smart Irrigation



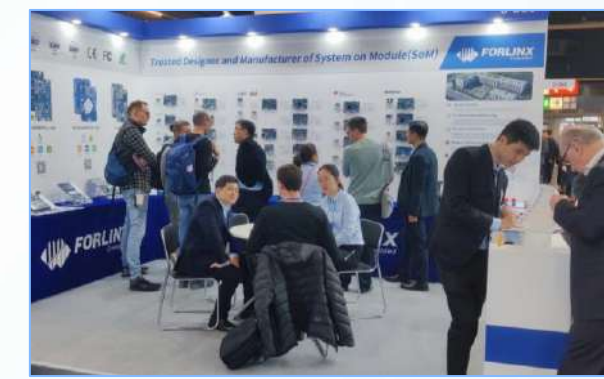
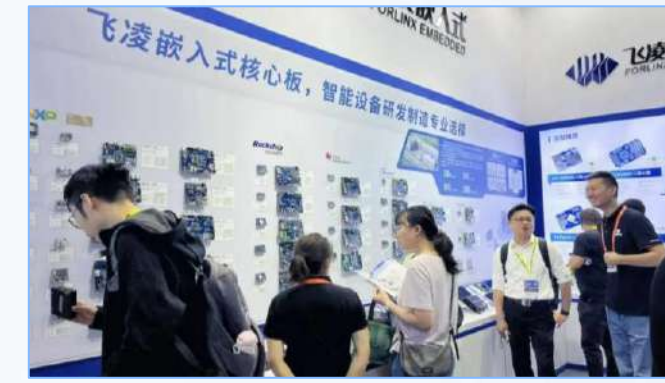
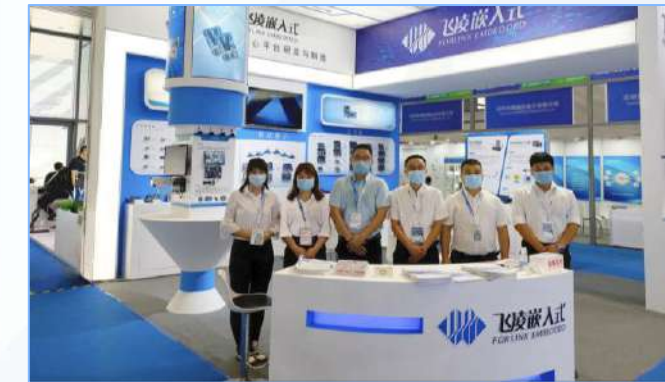
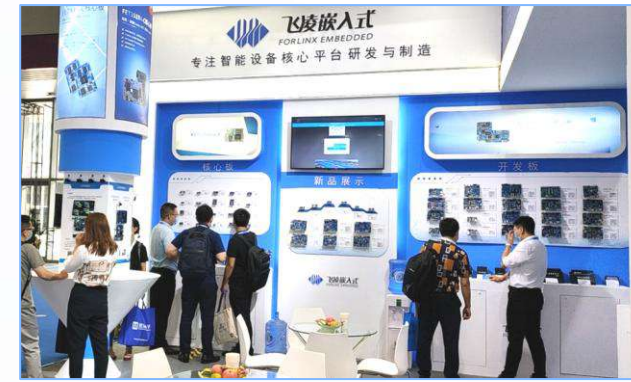
MARKETING

5

Marketing Channels

Forlinx Embedded adopts a hybrid online and offline marketing approach, establishing a comprehensive sales system that integrates online channels such as its official website and e-commerce platforms with offline channels including exhibitions, regional offices, and local agencies. Its business coverage extends nationwide, enabling prompt responses to customer needs while providing professional technical support and business collaboration services.

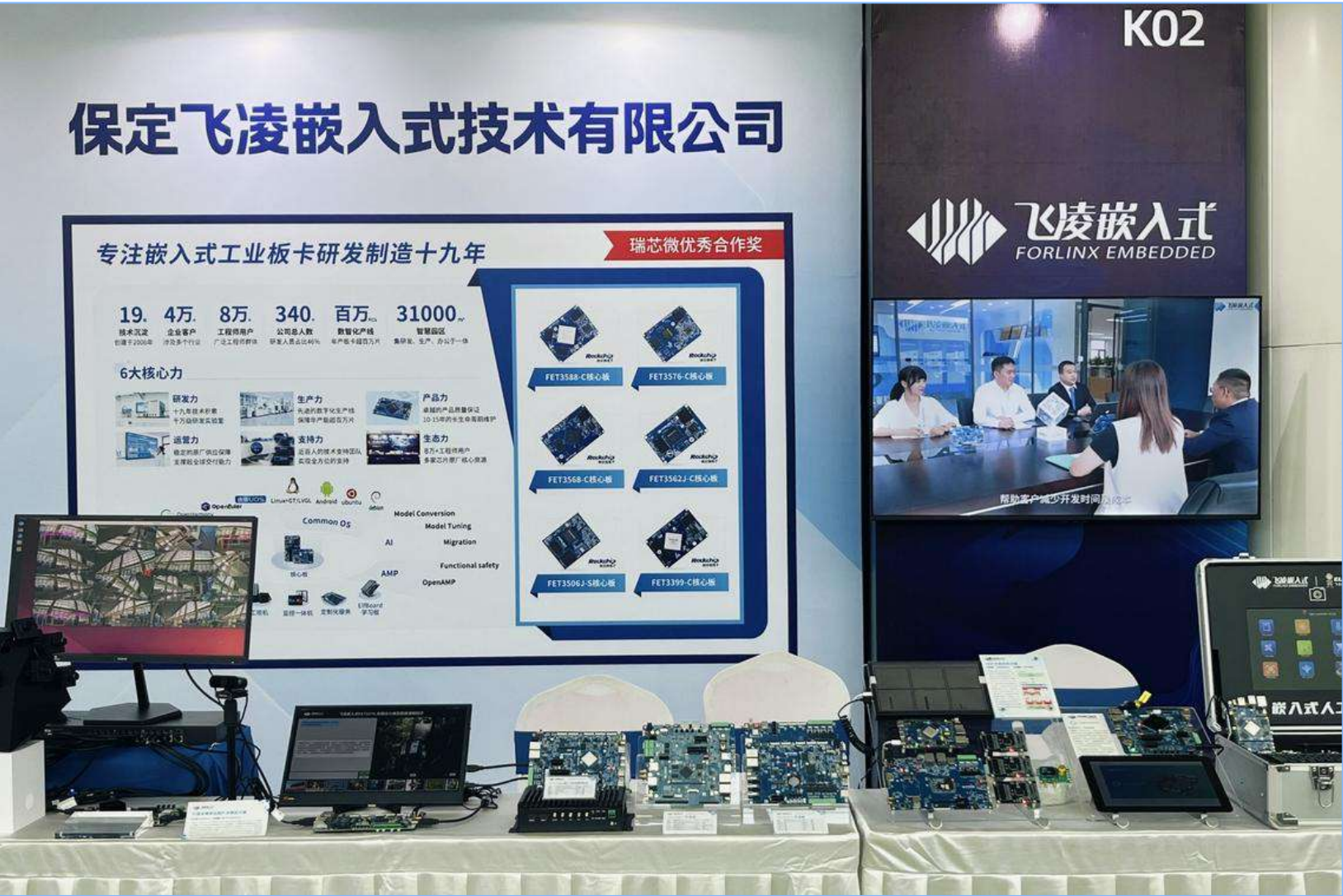




Exhibition Showcase

Participate in dozens of exhibitions every year, including the **Embedded World** in Nuremberg, Germany; the **Electronica** in Munich, Germany; the Embedded Exhibition in Shenzhen; **The China International Industry Fair**; the **CMEF**; and the **CACLP Medical Expo**.

ECO Collaboration



Invited to Exhibit at the 2025 Rockchip Ecosystem Conference



University-Enterprise Collaboration



Ecosystem Partner Seminars



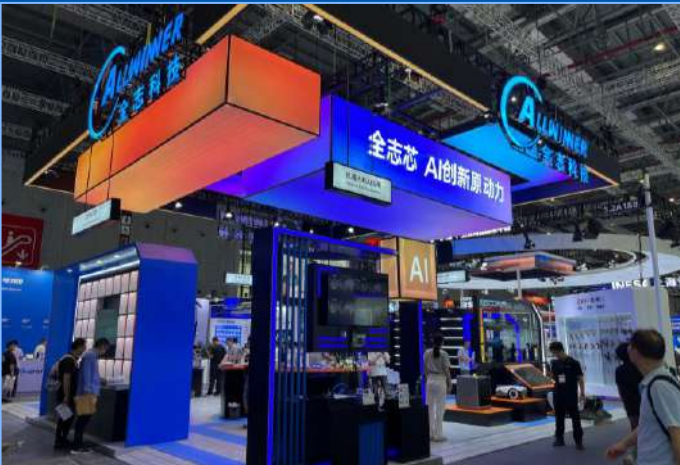
Invited to Exhibit at the 2025 NXP Technology Day Roadshow



Invited to Exhibit at the 2024 Texas Instruments Embedded Technology Innovation and Development Seminar



Joint Exhibition with Rockchip at the 2025 China International Industry Fair (CIIF)



Joint Exhibition with Allwinner at the 2025 China International Industry Fair (CIIF)

Global Distribution

Our customer and sales network covers the entire nation as well as regions including North America, Europe, and Asia-Pacific, with products sold in 79 countries.



THANK YOU!

FROM FORLINX
